EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	66	plasma adj polymeric	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 10:44
L2	18	1 and wafer	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 10:45
L3	34	1 and adhes$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 10:45
L4	17	2 and semiconductor	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 10:45
L5	4127	plasma adj polymer$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 10:48
L6	841	5 and semiconductor	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 10:48
L7	521	plasma adj polymer$4 same adh$6	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 10:48
L8	532	plasma adj polymer$4 same adhe$6	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 10:48

L9	841	6 and semiconductor	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 10:49
L10	104	8 and semiconductor	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 10:49
L11	72	10 and (handle or carrier or transfer or holder)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 10:49
L12	39	plasma adj polymer$4 same adhe$6 same (handle or carrier or transfer or holder)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 10:50
L13	8	12 and semiconductor	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 10:50
L14	1	plasmapolymeric	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 10:53
L15	152	Jakob.in. and polymeric	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 10:53
L16	49	15 and carrier	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 10:53
L17	3	16 and semiconductor	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 10:54

L18	0	Jakob.in. and plasma adj polymeric	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 10:55
L19	0	Jakob.in. and plasma with polymeric	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 10:55
L20	6097	plasma with polymer$3 and carrier	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 10:55
L21	1417	20 and semiconductor and adhe$5	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 10:56
L22	824	21 and wafer	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 10:56
L23	121	22 and detach$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 10:57
L24	100	plasma with polymer$3 same carrier same adhe$6	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 11:01
L25	41	24 and semiconductor	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 11:01
L26	32	25 and detach$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 11:02

L27	7535	plasma with polymer$3not clean$3 same carrier same adhe$6	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 11:03
L28	24231	plasma with polymer$3 not clean$3 same carrier same adhe$6	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 11:03
L29	7	26 NOT clean$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 11:04
L30	7	plasma adj polymer$3 same carrier same adhe$6	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 11:05
L31	600	plasma adj polymerization and semiconductor and carrier	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 11:07
L32	1872558	plasma adj polymerizationwith carrier	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 11:07
L33	128	plasma adj polymerization with carrier	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 11:07
L34	0	33 and semicondcutor	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 11:08
L35	16	33 and semiconductor	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 11:08

L36	129	plasma adj polymer$6 with carrier	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 11:11
L37	13	plasma adj polymer$6 with carrier same adhe$5	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 11:11
L38	19	plasma adj polymer$6 with (handle or carrier or transfer or holder) same adhe$5	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 11:14
L39	9	"6573156"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 11:18
L40	16	handling same plasma adj polymer$5	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 11:18
L41	0	40 and semicondcutor	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 11:19
L42	0	40 and semiconductor	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 11:20
L43	6	("20030175525" | "20040104272" | "5268065").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 11:21
L44	2	"20040041269".PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 11:21

L45	2	43 and plasma with polymer $4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 11:22
L46	2	43 and plasma with polymer $6	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 11:23
L47	0	("2004/0041269").URPN.	USPAT	OR	ON	2008/09/30 11:30
L48	1322	438/460.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 11:31
L49	2	48 and plasma adj polymer $6	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 11:32
L50	3698	438/460-464.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 11:33
L51	2	50 and plasma adj polymer $6	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 11:33
L52	424	plasma with polymer$3 and substrate and semiconductor and adhe$6 and detach$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 11:35
L53	2893	plasma with polymer$3 and substrate and semiconductor and adhe$6 and (detach$4 or separat$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 11:35
L54	3148	plasma with polymer$3 same adhe$5	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 11:36

L55	2447296	plasma with polymer$3with adhe$5	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 11:36
L56	1853	plasma with polymer$3 with adhe$5	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 11:36
L57	129	plasma adj polymer$3 with adhe$5	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 11:37
L58	13	53 and (plasma adj polymer $3 with adhe$5)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/30 11:37

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